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(54) Title: A METHOD OF SPUTTER DEPOSITION OF A FILM ON AN ESSENTIALLY PLANE EXTENDED SURFACE OF A SUBSTRATE

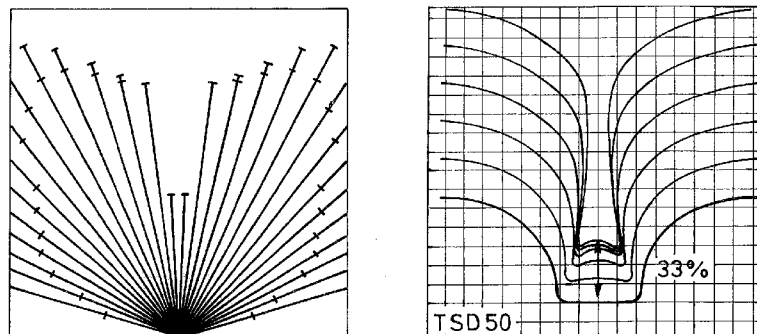


FIG.1a

(57) Abstract: A film is sputter-deposited on an essentially plane, extended surface of a substrate which has recesses therein, namely at least one of grooves, of holes, of bores, of vias, of trenches. So as to establish on one hand a homogeneous thickness distribution of the film along the addressed surface of the substrate and, on the other hand, a thick film deposition within the recesses, sputter deposition is performed first at a large distance between a sputter surface of a target and the addressed surface of the substrate and then at a reduced distance between the addressed surfaces.